

February 22, 2005

Ohmega Technologies Inc.

OHMEGA TECHNOLOGIES AND OAK-MITSUI TECHNOLOGIES INTRODUCE NEW EMBEDDED PASSIVE PRODUCT

Ohmega-Ply[®] /FaradFlex[®] Embedded Resistor-Capacitor Layer

Culver City, CA (February 22, 2005)--Ohmega Technologies, Inc. is pleased to announce, that in collaboration with Oak-Mitsui Technologies, the joint development of a new embedded passive product that combines their two industry-leading embedded passives products: Ohmega-Ply[®] thin-film embedded resistor material and FaradFlex[®] distributed capacitive material.

The combination of these two embedded passive materials creates a new patent pending resistor/capacitor core offering the printed circuit design engineer the ability to incorporate both embedded resistors and a distributed capacitive plane onto one core within a multilayer printed circuit board.

The new product is an Ohmega-Ply[®]/FaradFlex[®] laminate consisting of Ohmega-Ply RCM[®] laminated to FaradFlex[®] BC24M dielectric available in sheet resistances of 10 ohm, 25 ohm, 50 ohm, 100 ohm or 250 ohm per square. Further dielectric offerings are planned for future release.

“We are excited with the synergy of these two embedded passive products. With the growing use of embedded passives in printed circuit boards, designers are faced with the daunting task of packaging more electronic circuitry into smaller, thinner and denser form factors. The combined Ohmega-Ply[®]/FaradFlex[®] product allows for fewer circuit layers and greater densities,” said Bruce Mahler, Vice President of Ohmega Technologies, Inc.

For more information on Ohmega-Ply[®]/FaradFlex[®] please contact:

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About Ohmega Technologies, Inc.

Ohmega Technologies, Inc. is the industry leading producer of embedded resistor materials with its Ohmega-Ply[®] family of innovative thin-film resistive materials. Ohmega-Ply[®] has been in production and use for over three decades with unsurpassed reliability in a wide variety of electronic applications. For more information on Ohmega Technologies' products, please visit www.ohmega.com

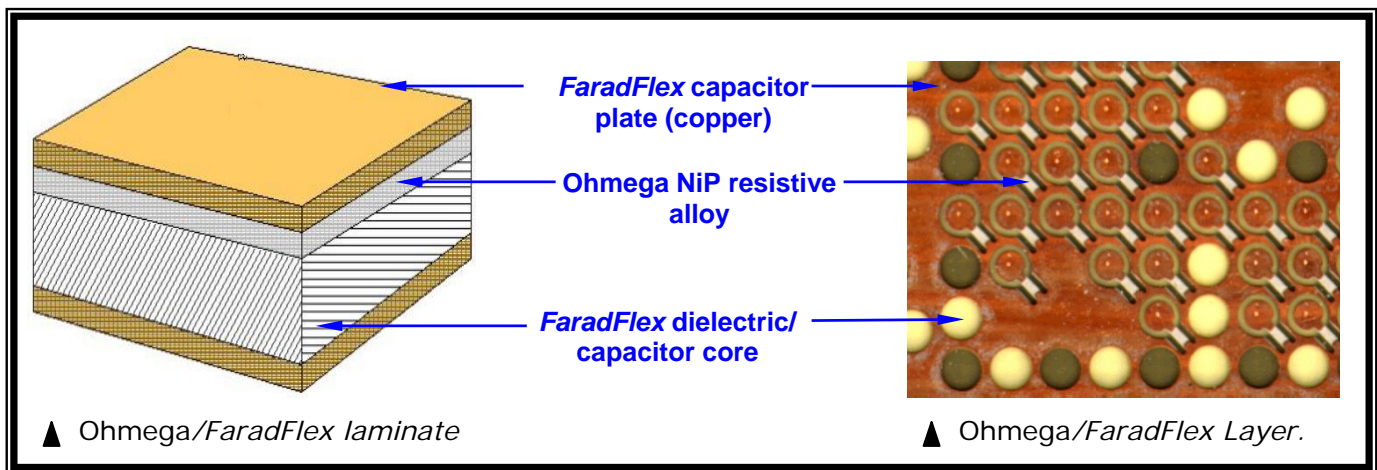
About Oak-Mitsui Technologies, LLC

Oak-Mitsui Technologies is a subsidiary of copper foil producer Oak-Mitsui. Oak-Mitsui specializes in the development and production of world-class performance copper foils and advanced materials for electronic interconnect applications. Oak-Mitsui is a subsidiary of Mitsui Kinzoku Corporate Group, the world's largest manufacturer of copper foils for electronics and is a licensee of Sanmina-SCI Buried Capacitance Technology. For additional information concerning Oak-Mitsui products, please visit www.oakmitsui.com.

Ohmega[®]/FaradFlex[®]

EMBEDDED RESISTANCE-CAPACITANCE TECHNOLOGY

Ohmega[®]/FaradFlex[®] is a combined product of the OhmegaPly[®] thin film resistive-conductive material (RCM) laminated to a FaradFlex[®] dielectric material and subtractively processed to produce embedded RC Networks.



- Combined Laminate Product.
- Resistance and Capacitance in the same core.
- Developed to accommodate high density designs.
- Embedded Resistor and Capacitor Networks
- Improved signal integrity by better impedance matching.
- Improved signal to noise ratios.
- Standard PCB Subtractive Processing.
- Greater cost effectiveness than separate BR and BC cores.

OHMEGA/FARADFLEX SPECIFICATIONS AND PROPERTIES for 1R25 / BC24

1-Oak-Mitsui Properties

OAK-MITSUI TECHNOLOGIES

MITSUBI KINZOKU CORPORATE GROUP



Properties	Ohmega/FaradFlex Core	Remarks and Conditions
Copper Weight, μm	35	Nominal
Sheet Resistivity, ohms / square	25	Nominal
Dielectric Thickness, μm	24	Nominal
Cp@ 1MHz, nF/in ² (pF/cm ²)	1.0 (155)	IPC-TM 650 2.5.5.3
Dk @1MHz	4.4	IPC-TM 650 2.5.5.3
Loss Tangent @ 1MHz	0.015	IPC-TM 650 2.5.5.3
Peel Strength, lbs/in	5.0	IPC-TM 650 2.4.9
Dielectric Strength, kV/mil	5.3	IPC-TM 650 2.5.6.3
Tensile Strength, Mpa(kpsi)	152(22.0)	ASTM D-882 A
Elongation, %	18.5	ASTM D-882 A

2-OhmegaPly Properties



Properties	Ohmega/FaradFlex Core	Ohmega Core FR-4 (control)	Remarks and Conditions
Sheet Resistivities (ohm/square)	25	25	Nominal
Material Tolerance	+/-5%	+/-5 %	
Load Life Cycling Test Resistor Size: 0.500" X 0.050" Loaded: (Δ R%) @ 150mW Unloaded: (Δ R%)	<0.90 after 3200 hrs.) <0.74 after 3200 hrs.)	<5	MIL-STD-202-108I Ambient Temp: 70C On Cycle: 1.5 hrs Off Cycle: 1.5 hrs Length Of Test: 10000 hrs
Current Noise Index in dB	<-23	<-15	MIL-STD-202-308 Voltage Applied: 5.6 Volts
Humidity Test (Δ R%)	0.5	0.5	MIL-STD-202-103A Temp: 40 °C Relative Humidity: 95% Time: 240 hrs
Characteristic (RTC) PPM°C	-6.0	50	MIL-STD-202-304 Hot Cycle: 25°, 50°, 75° 125°C Cold Cycle: 25°, 0°, -25°, -55°C
Thermal Shock (Δ R%)	0.2	-0.5	MIL-STD-202-107B No of Cycles: 25 Hot Cycle Temp: 125 °C Cold Cycle Temp: -65 °C
Solder Float (Δ R%) After 1 Cycle After 5 cycles	-0.4 -0.6	0.5	MIL-STD-202-210D Temp: 260°C Immersion: 20 Second
Power Density (mW/mil ²) derated at 50%	0.45	0.15	Step-up Power Test Resistor Size: 0.020" X 0.030"